

SN54ALS193A, SN74ALS193A
SYNCHRONOUS 4-BIT UP/DOWN BINARY COUNTERS
WITH DUAL CLOCK AND CLEAR
SDAS211C – DECEMBER 1982 – REVISED JULY 1996

- **Look-Ahead Circuitry Enhances Cascaded Counters**
- **Fully Synchronous in Count Modes**
- **Parallel Asynchronous Load for Modulo-N Count Lengths**
- **Asynchronous Clear**
- **Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs**

description

The 'ALS193A are synchronous, reversible, 4-bit up/down binary counters. Synchronous counting operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the steering logic. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters.

The outputs of the four flip-flops are triggered on a low-to-high-level transition of either count/clock (UP or DOWN) input. The direction of the count is determined by which count input is pulsed while the other count input is high.

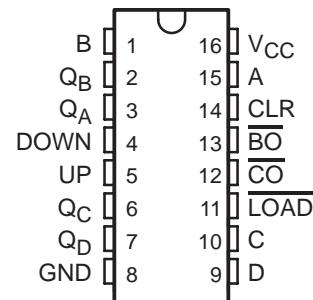
All four counters are fully programmable; that is, each output may be preset to either level by placing a low on the load (LOAD) input and entering the desired data at the data inputs. The output changes to agree with the data inputs independently of the count pulses. This feature allows the counters to be used as modulo-N dividers by simply modifying the count length with the preset inputs.

A high level applied to the clear (CLR) input forces all outputs to the low level. The clear function is independent of the count and LOAD inputs. The UP, DOWN, and LOAD inputs are buffered to lower the drive requirement, which significantly reduces the loading on, or current required by, clock drivers, etc., for long parallel words.

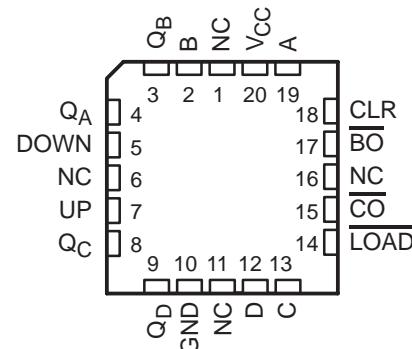
These counters are designed to be cascaded without the need for external circuitry. The borrow (\overline{BO}) output produces a low-level pulse while the count is zero (all Q outputs low) and the DOWN input is low. Similarly, the carry (\overline{CO}) output produces a low-level pulse while the count is 9 or 15 (all Q outputs high) and the UP input is low. The counters can then be easily cascaded by feeding \overline{BO} and \overline{CO} to the count-down and count-up inputs, respectively, of the succeeding counter.

The SN54ALS193A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS193A is characterized for operation from 0°C to 70°C .

SN54ALS193A . . . J PACKAGE
SN74ALS193A . . . D OR N PACKAGE
(TOP VIEW)



SN54ALS193A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



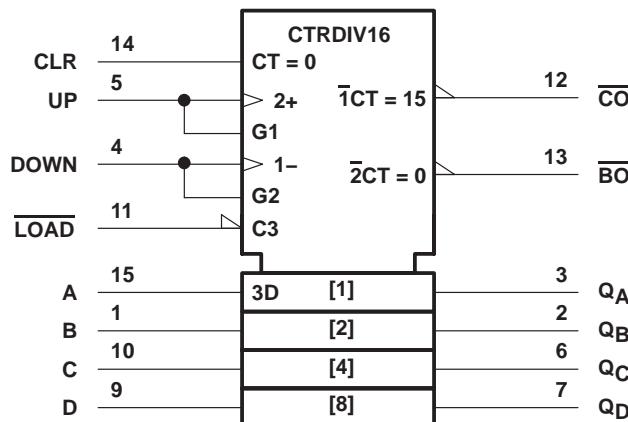
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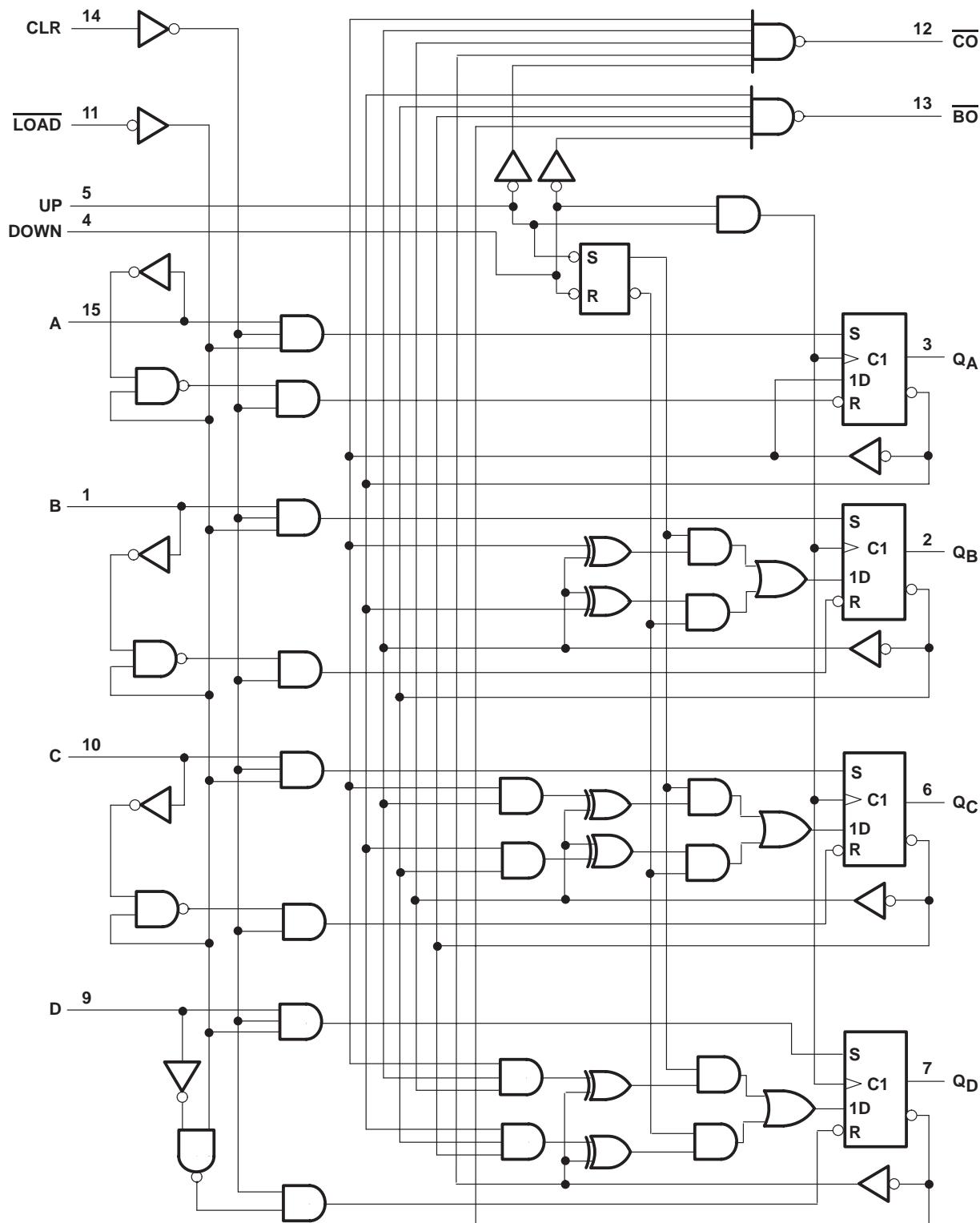
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.

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logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

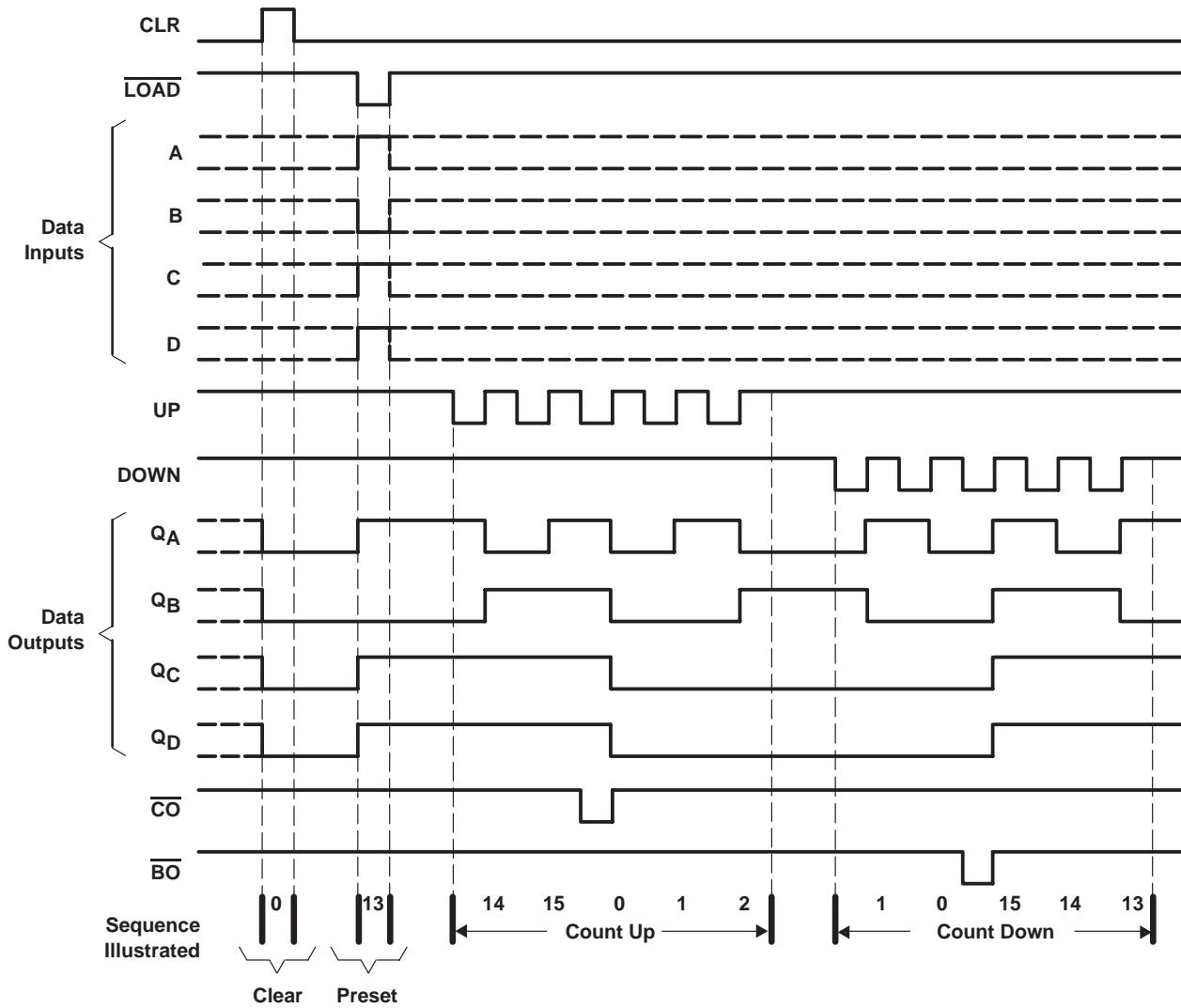
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typical clear, load, and count sequence

the following sequence is illustrated below:

1. Clear outputs to zero
2. Load (preset) to binary 13
3. Count up to 14, 15 (carry), 0, 1, and 2
4. Count down to 1, 0 (borrow), 15, 14, and 13



NOTES: A. Clear overrides load, data, and count inputs.
B. When counting up, count-down input must be high; when counting down, count-up input must be high.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54ALS193A			SN74ALS193A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.7			0.8	V
I _{OH}	High-level output current				-0.4			-0.4	mA
I _{OL}	Low-level output current				4			8	mA
f _{clock}	Clock frequency		0		20	0		30	MHz
t _W	Pulse duration	CLR high		10		10			ns
		LOAD low		25		20			
		UP or DOWN high or low		30		16.5			
t _{su}	Setup time	Data before LOAD↑		25		20			ns
		CLR inactive before UP or DOWN		20		20			
		LOAD inactive before UP or DOWN		20		20			
t _h	Hold time	Data after LOAD↑		5		5			ns
		UP high after DOWN↑		5		0			
		DOWN high after UP↑		5		0			
T _A	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS193A			SN74ALS193A			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = 4.5 \text{ V}$, $I_I = -18 \text{ mA}$			-1.5			-1.5	V
V_{OH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $I_{OH} = -0.4 \text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
V_{OL}	$V_{CC} = 4.5 \text{ V}$	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4
		$I_{OL} = 8 \text{ mA}$					0.35	0.5
I_I	$V_{CC} = 5.5 \text{ V}$, $V_I = 7 \text{ V}$			0.1		0.35	0.1	mA
I_{IH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 2.7 \text{ V}$			20			20	μA
I_{IL}	UP or DOWN			-0.2			-0.2	mA
	All others	$V_{CC} = 5.5 \text{ V}$, $V_I = 0.4 \text{ V}$		-0.1			-0.1	
$I_O\$$	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.25 \text{ V}$	-20	-112	-30	-112			mA
I_{CC}	$V_{CC} = 5.5 \text{ V}$, See Note 1		12	22		12	22	mA

[‡]All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

NOTE 1: I_{CC} is measured with the clear and load inputs grounded and all other inputs at 4.5 V.

§ The output conditions have been chosen to produce a current that closely approximates one half of the maximum output current of the device.
NOTE 1: I_{CC} is measured with the clear and load inputs grounded and all other inputs at 4.5 V.



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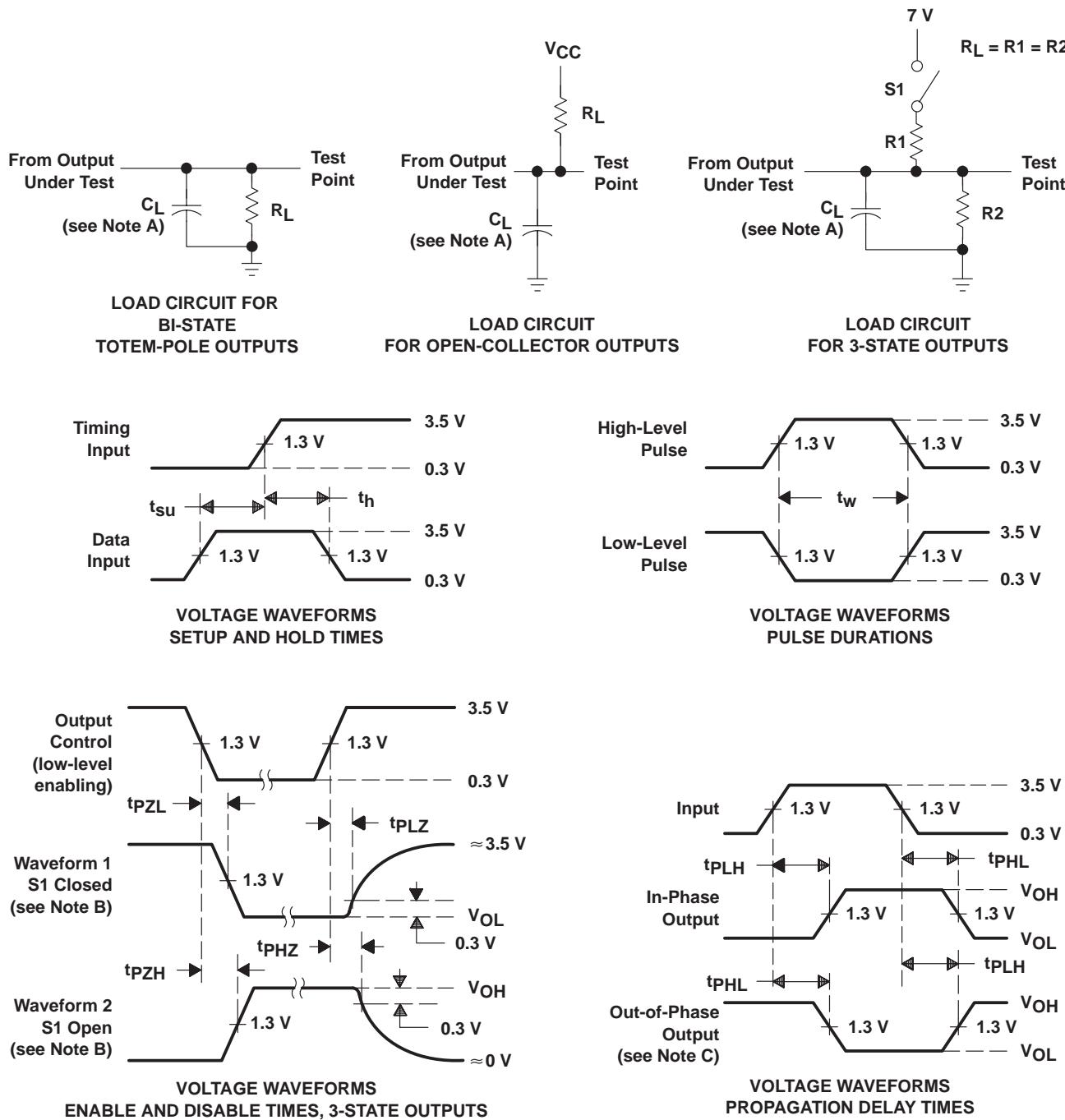
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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R1 = R2 = 500 \Omega$, $T_A = \text{MIN to MAX}^{\dagger}$				UNIT	
			SN54ALS193A		SN74ALS193A			
			MIN	MAX	MIN	MAX		
f_{max}			25		30		MHz	
t_{PLH}	UP	\overline{CO}	3	20	3	16	ns	
t_{PHL}			3	21	5	18		
t_{PLH}	DOWN	\overline{BO}	4	20	4	16	ns	
t_{PHL}			5	22	5	18		
t_{PLH}	UP or DOWN	Any Q	3	27	3	19	ns	
t_{PHL}			4	23	4	17		
t_{PLH}	$\overline{\text{LOAD}}$	Any Q	7	38	7	30	ns	
t_{PHL}			8	37	8	28		
t_{PHL}	CLR	Any Q	5	20	5	17	ns	

[†] For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

**PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES**



NOTES:

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-88698012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-88698012A SNJ54ALS193AFK	Samples
5962-8869801EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8869801EA SNJ54ALS193AJ	Samples
5962-8869801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8869801FA SNJ54ALS193AW	Samples
SN54ALS193AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS193AJ	Samples
SN74ALS193AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS193A	Samples
SN74ALS193ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS193A	Samples
SN74ALS193ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS193A	Samples
SN74ALS193ADR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70	ALS193A	
SN74ALS193ADRE4	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74ALS193ADRG4	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74ALS193AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS193AN	Samples
SN74ALS193ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS193AN	Samples
SN74ALS193ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS193A	Samples
SN74ALS193ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS193A	Samples
SN74ALS193ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS193A	Samples
SNJ54ALS193AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-88698012A SNJ54ALS193AFK	Samples
SNJ54ALS193AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8869801EA SNJ54ALS193AJ	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54ALS193AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8869801FA SNJ54ALS193AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ALS193A, SN74ALS193A :

- Catalog: [SN74ALS193A](#)



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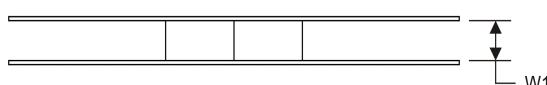
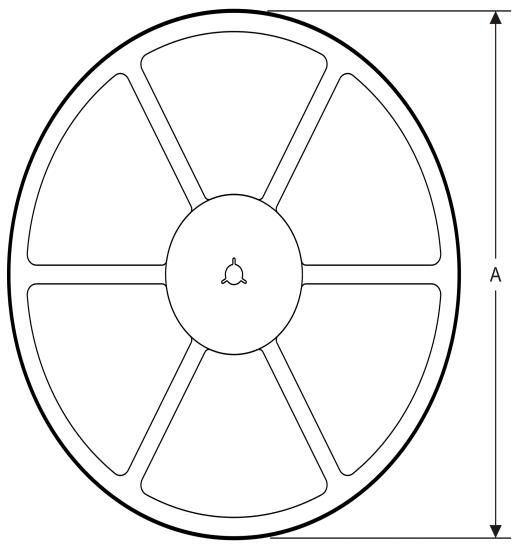
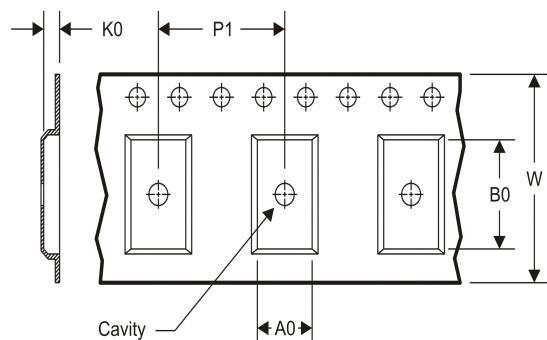
PACKAGE OPTION ADDENDUM

25-Sep-2013

- Military: [SN54ALS193A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

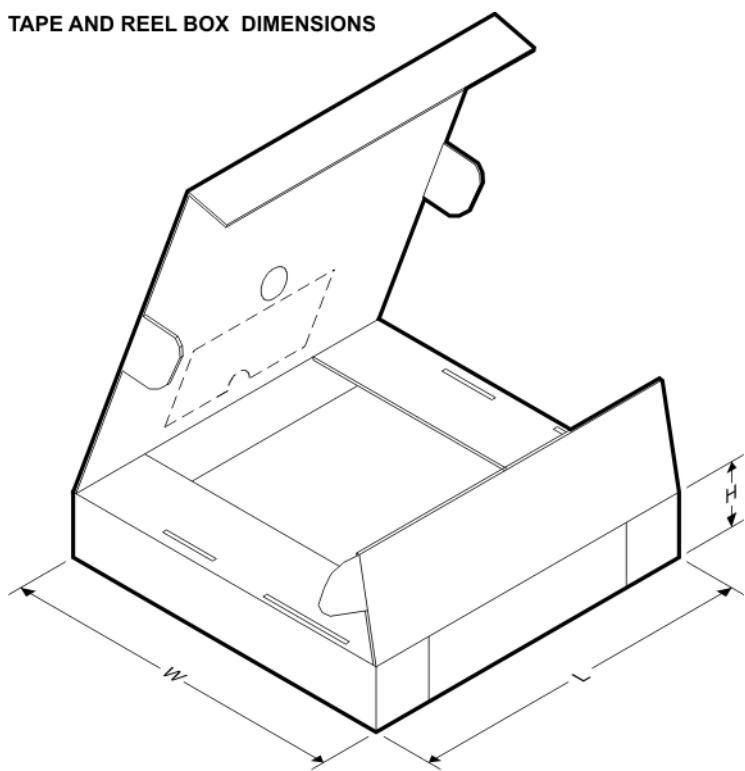
TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS193ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS193ANSR	SO	NS	16	2000	367.0	367.0	38.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

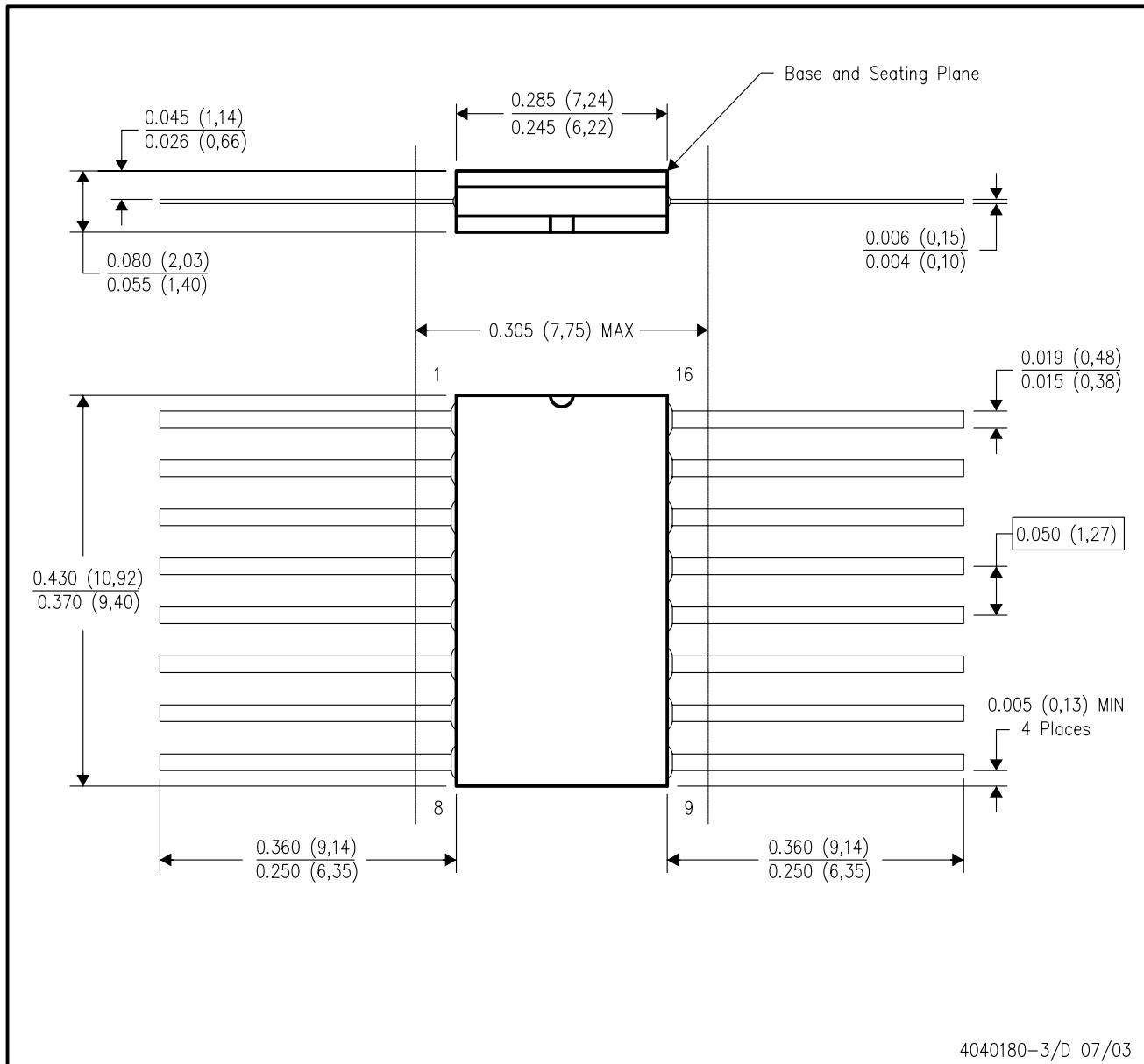


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



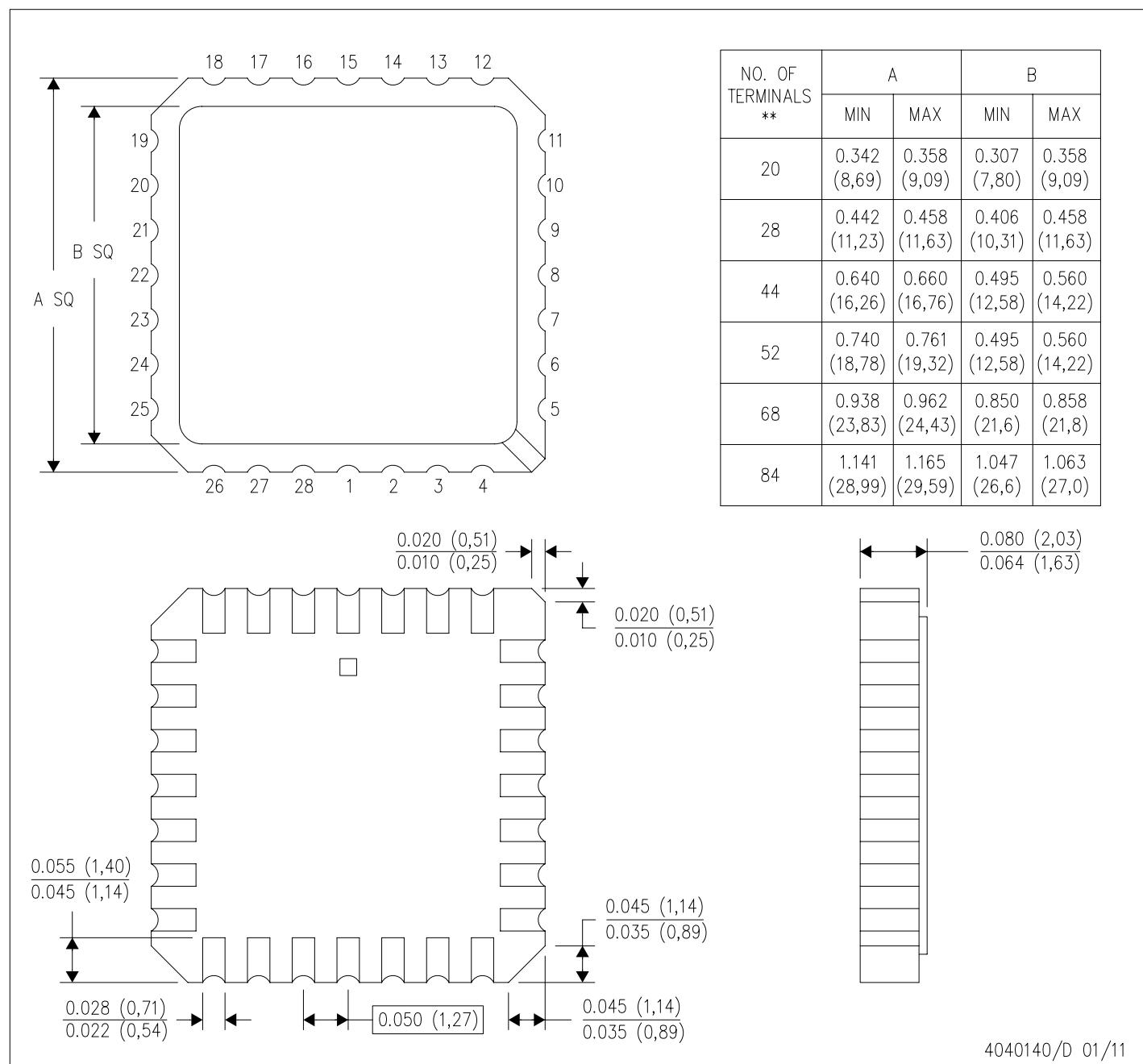
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

N (R-PDIP-T**)

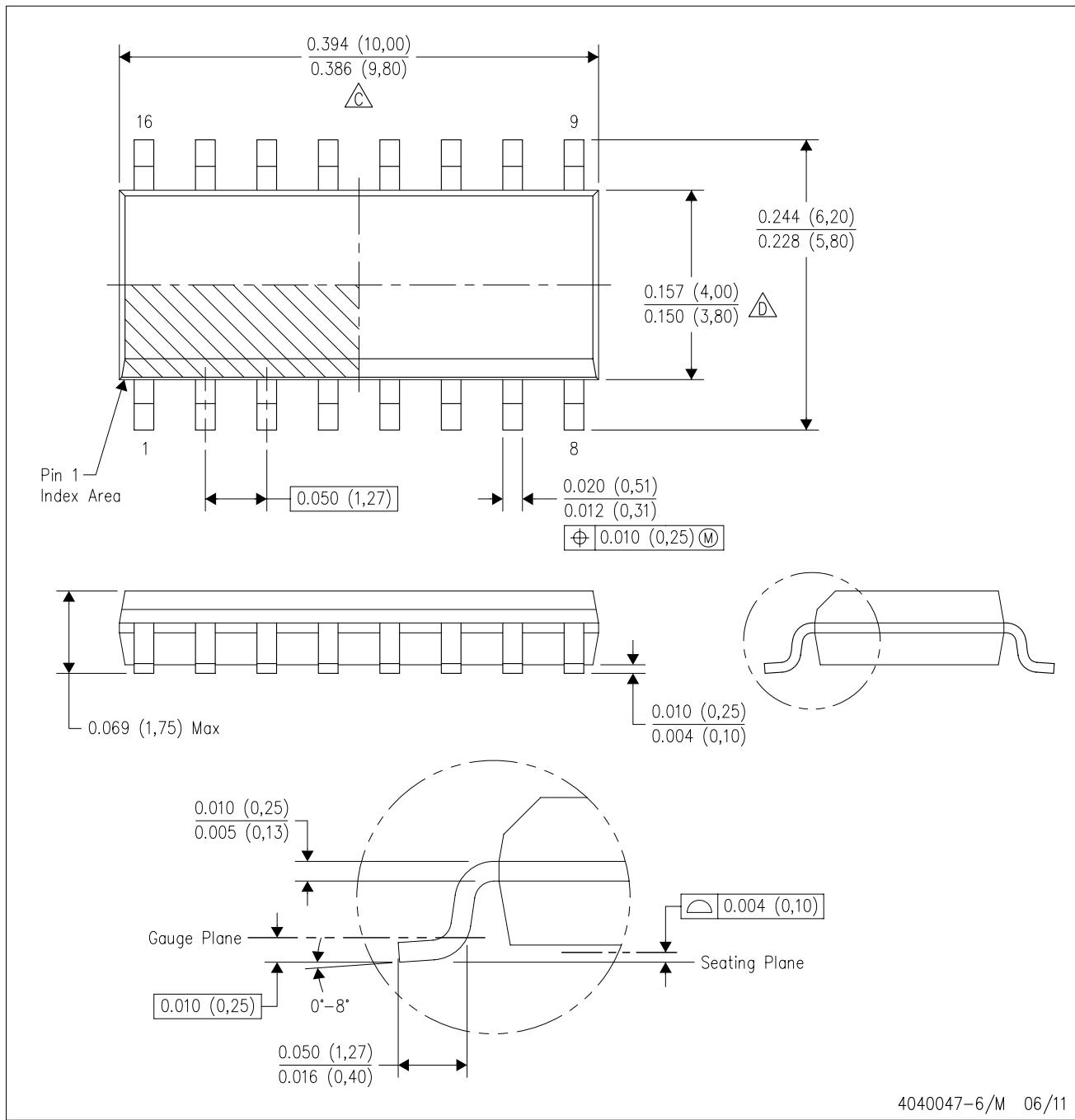
16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

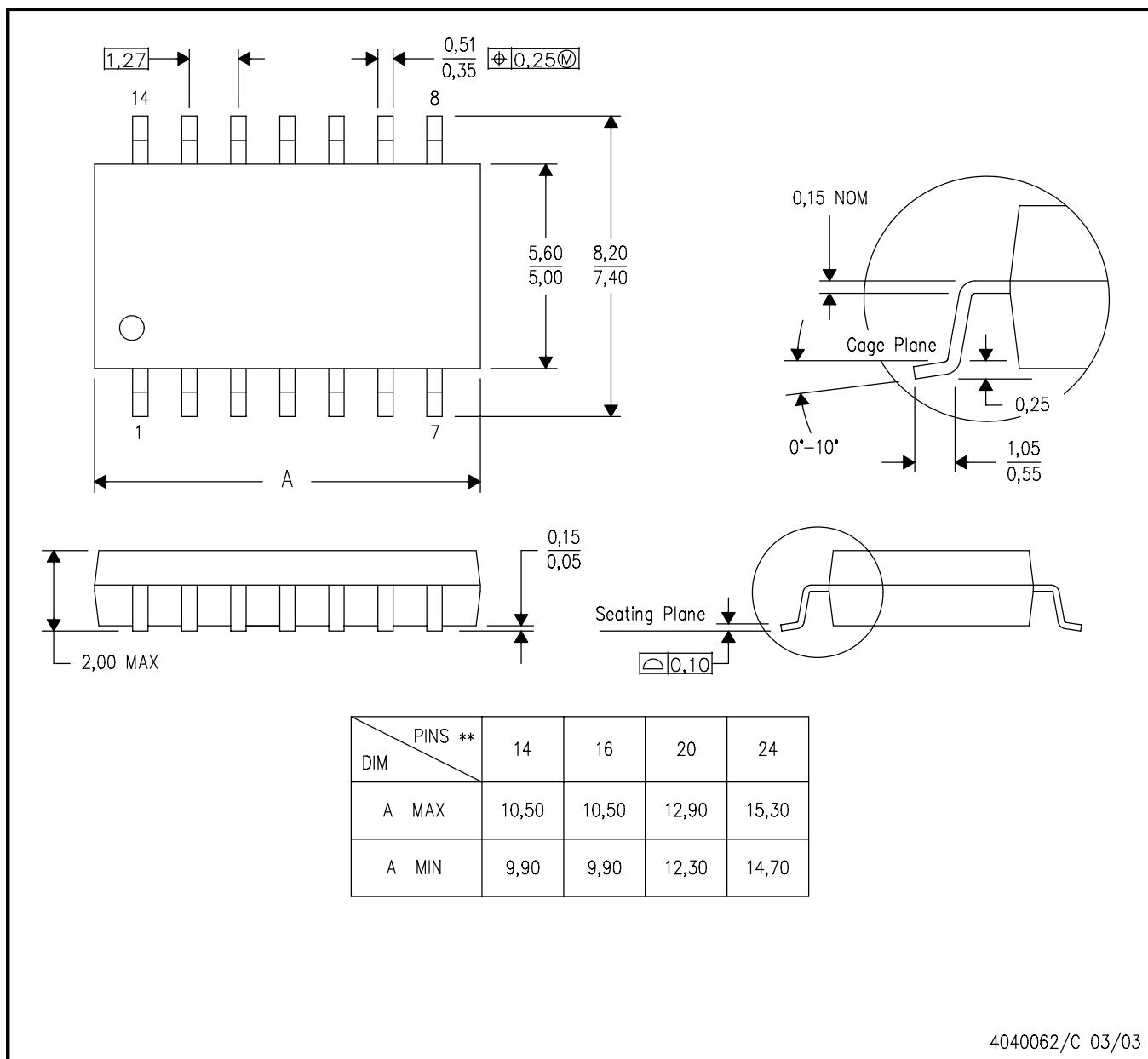
E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

4040062/C 03/03

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